# Silicon Carbide Schottky Diode

# 1200 V, 20 A

# **FFSP20120A**

### Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

#### Features

- Max Junction Temperature 175°C
- Avalanche Rated 200 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- This Device is Pb–Free, Halogen Free/BFR Free and RoHS Compliant

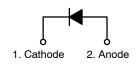
#### Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

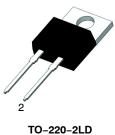


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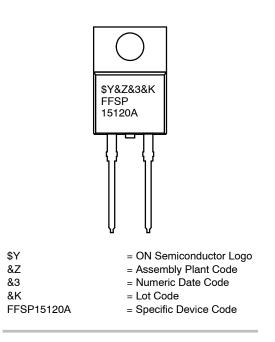


Schottky Diode



TO-220-2LD CASE 340BB

### MARKING DIAGRAM



#### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

## **FFSP20120A**

Symbol	Parameter		Value	Unit
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage		1200	V
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 1)		200	mJ
١ <sub>F</sub>	Continuous Rectified Forward Current @ T <sub>C</sub> < 148°C		20	A
I <sub>F,Max</sub>	Non-Repetitive Peak Forward Surge Current	T <sub>C</sub> = 25°C, 10 μs	1190	A
		T <sub>C</sub> = 150°C, 10 μs	990	A
I <sub>F,SM</sub>	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t <sub>p</sub> = 8.3 ms	135	A
I <sub>F,RM</sub>	Repetitive Forward Surge Current	Half-Sine Pulse, t <sub>p</sub> = 8.3 ms	74	A
P <sub>TOT</sub>	Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	340	W
		T <sub>C</sub> = 150°C	57	W
TJ, T <sub>STG</sub>	Operating and Storage Temperature Range	•	–55 to +175	°C

#### **ABSOLUTE MAXIMUM RATINGS** (T<sub>C</sub> = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1.  $E_{AS}$  of 200 mJ is based on starting  $T_J$  = 25°C, L = 0.5 mH,  $I_{AS}$  = 29 A, V = 150 V.

#### THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	0.44	°C/W

#### ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V <sub>F</sub>	Forward Voltage	$I_{F} = 20 \text{ A}, T_{C} = 25^{\circ}\text{C}$	-	1.45	1.75	V
		$I_{F} = 20 \text{ A}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	1.7	2.0	
		I <sub>F</sub> = 20 A, T <sub>C</sub> = 175°C	-	2.0	2.4	
I <sub>R</sub>	Reverse Current	$V_{\rm R}$ = 1200 V, $T_{\rm C}$ = 25°C	-	-	200	μΑ
		$V_{\rm R}$ = 1200 V, $T_{\rm C}$ = 125°C	-	-	300	
		$V_{\rm R}$ = 1200 V, $T_{\rm C}$ = 175°C	-	-	400	
Q <sub>C</sub>	Total Capacitive Charge	V = 800 V	-	120	-	nC
С	Total Capacitance	V <sub>R</sub> = 1 V, f = 100 kHz	-	1220	-	pF
		V <sub>R</sub> = 400 V, f = 100 kHz	-	111	-	1
		V <sub>R</sub> = 800 V, f = 100 kHz	-	88	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

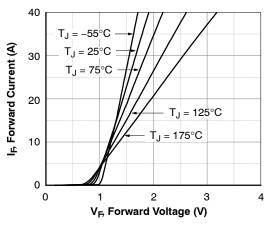
#### **ORDERING INFORMATION**

Part Number	Top Marking	Package	Packing Method	Quantity
FFSP20120A	FFSP20120A	TO-220-2LD	Tube	50 Units

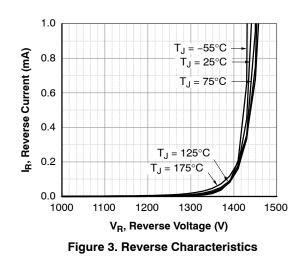
## **FFSP20120A**

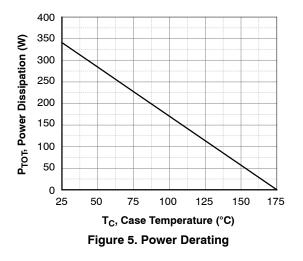
## **TYPICAL CHARACTERISTICS**

(T<sub>J</sub> = 25°C unless otherwise noted)



**Figure 1. Forward Characteristics** 





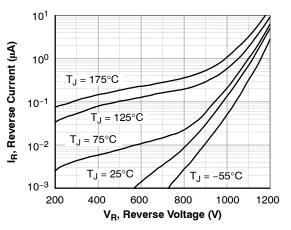
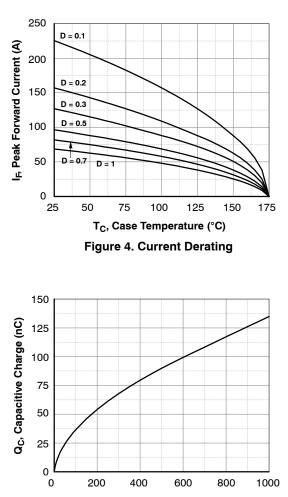


Figure 2. Reverse Characteristics



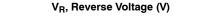


Figure 6. Capacitive Charge vs. Reverse Voltage

## **FFSP20120A**

#### TYPICAL CHARACTERISTICS (Continued)

(T<sub>J</sub> =  $25^{\circ}$ C unless otherwise noted)

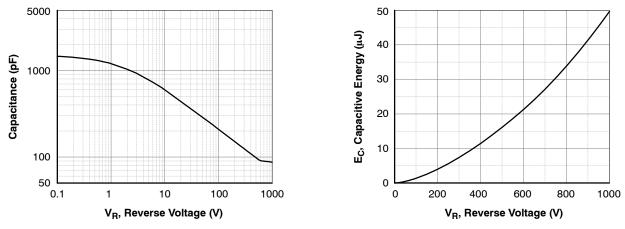
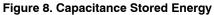
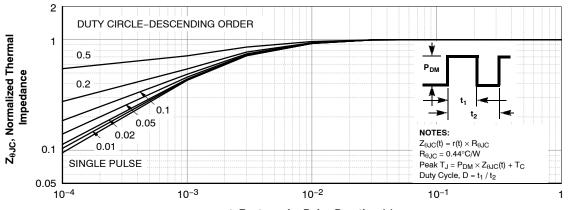


Figure 7. Capacitance vs. Reverse Voltage

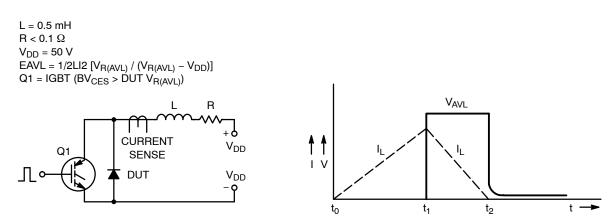




t, Rectangular Pulse Duration (s)

Figure 9. Junction-to-Case Transient Thermal Response Curve

#### **TEST CIRCUIT AND WAVEFORMS**

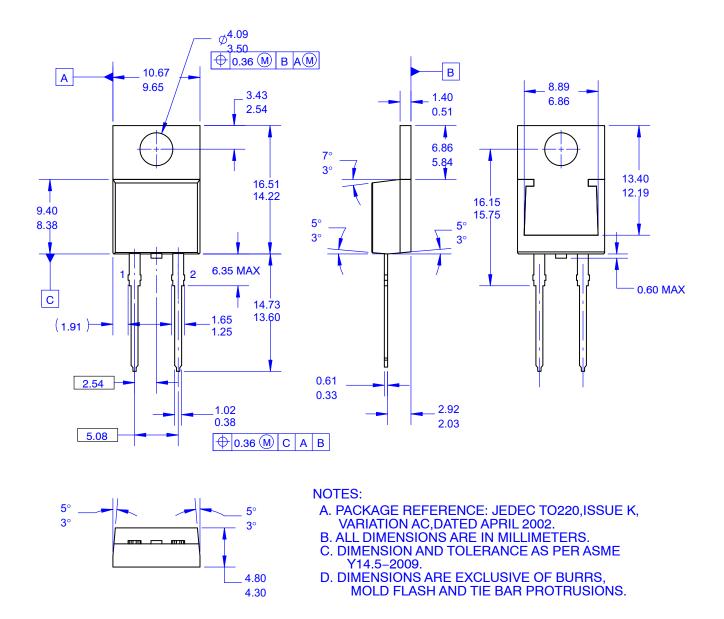






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DATE 31 AUG 2016



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